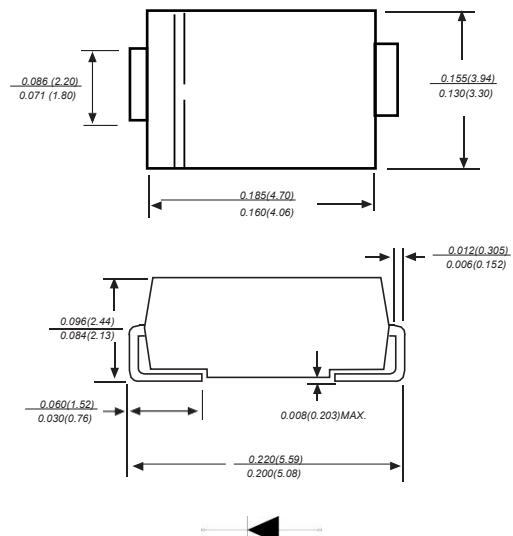


## SURFACE MOUNT GENERAL RECTIFIER

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Open Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed 250°C/10 seconds at terminals

**DO-214AA/SMB**



Dimensions in inches and (millimeters)

### Mechanical Data

Case : JEDEC SMB molded plastic body

Terminals : Solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body Mounting

Position : Any

Weight : 0.003ounce, 0.09grams

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

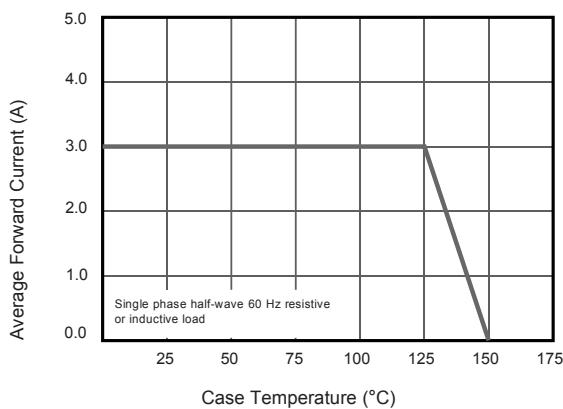
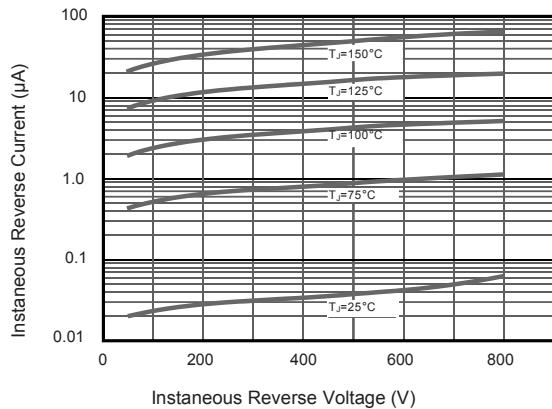
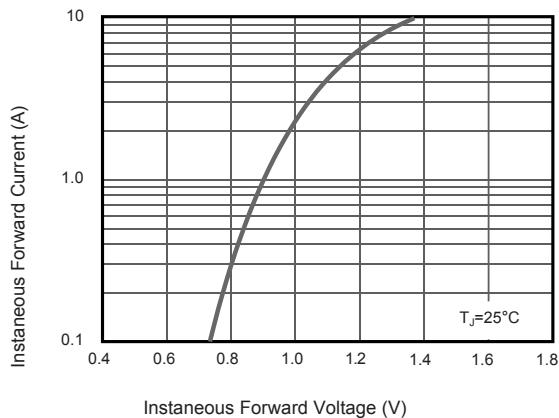
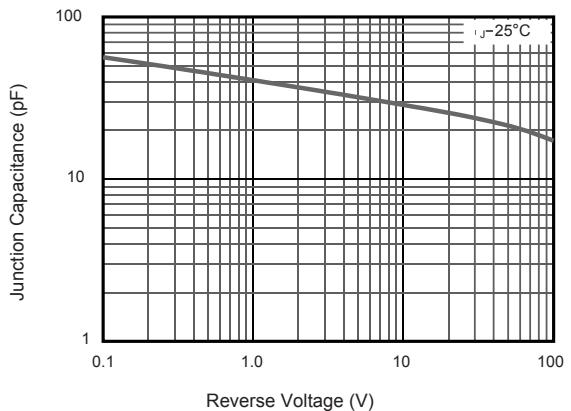
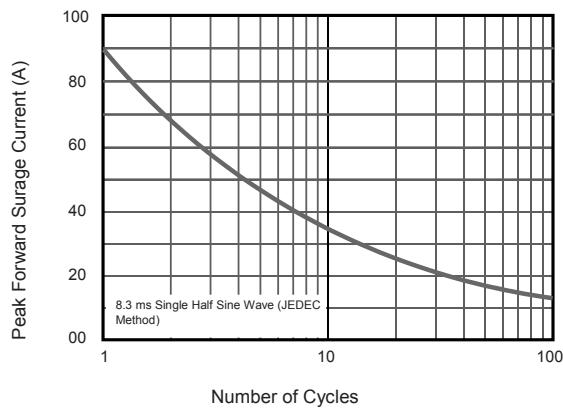
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	UNITS
		S3A	S3B	S3D	S3G	S3J	S3K	S3M	
Marking Code									
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I <sub>(AV)</sub>	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	90							A
Maximum instantaneous forward voltage at 3.0A	V <sub>F</sub>	1.1							V
Maximum DC reverse current    T <sub>A</sub> =25°C at rated DC blocking voltage    T <sub>A</sub> =125°C	I <sub>R</sub>	5 100							µA
Typical junction capacitance (NOTE 1)	C <sub>J</sub>	35							pF
Typical thermal resistance (NOTE 2)	R <sub>θJA</sub> R <sub>θJC</sub>	48 16							°C/W
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150							°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

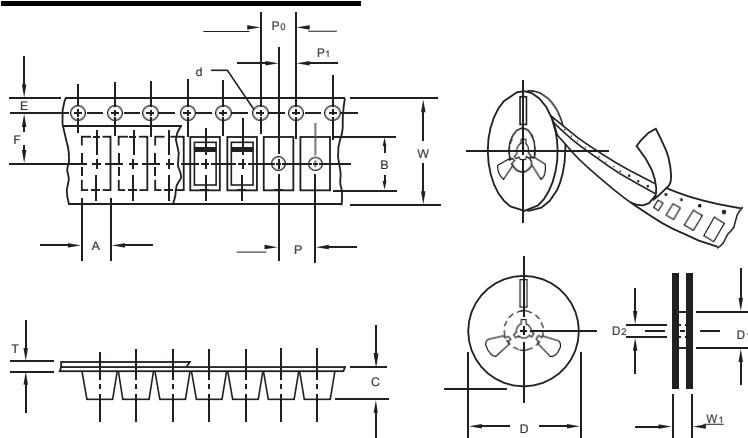
2.P.C.B. mounted with 2.0"x2.0"(5.0x5.0cm) copper pad areas

## Typical Characteristics

**Fig.1 Forward Current Derating Curve**

**Fig.2 Typical Instantaneous Reverse Characteristics**

**Fig.3 Typical Forward Characteristic**

**Fig.4 Typical Junction Capacitance**

**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**


The curve above is for reference only.

## Packing information



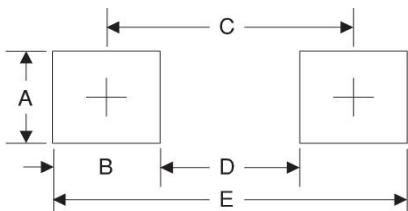
Item	Symbol	Tolerance	SMB
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.55
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W <sub>1</sub>	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB	13"	3,000	4.0	6,000	190*190*41	330	365*365*360	48,000	14.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.8	0.110
B	2.4	0.094
C	4.6	0.181
D	2.2	0.086
E	7.0	0.276